## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2021 to Q4/2021

Based on structural similarity
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Supplier		User Part Number					
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		PMEG4010EJ Part Description					
		SMD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
			TEST Pre- and Post-Stress				
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
# A1	<b>PC</b> Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	810	58300	0	
# B1	<b>HTRB</b> High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage <sup>[1]</sup>	1000 hours	116	9280	0	
	тс	JESD22-A104					
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	170	13600	0	
≠ A3 alt	<b>AC</b> Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	170	13600	0	
≠ A2 alt	<b>H3TRB</b> High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage <sup>[1], [2]</sup>	1000 hours	170	13600	0	
	IOL	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj$ =					
# A5	Intermittent Operating Life	100 °C 10F 15000 Cycles	1000 hours	170	13600	0	
+ C8	<b>RSH</b> Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	130	3900	0	
± C10	<b>SD</b> Solderability	J-STD-002		363	3630	0	

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	9280	0	0.46	2.19E+09
	Beneticity	200	5		21152.05

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